

Notice of References Cited	Application/Control No. 10/520,260	Applicant(s)/Patent Under Reexamination SVENDSEN ET AL	
	Examiner Daniel Swerdlow	Art Unit 2646	Page 1 of 1

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*	B	US-3,239,093	03-1966	TONY GATH	381/322
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	M	US-			

FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

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	U	Feldmann, K. et al., Automated assembly of new 3D molded interconnect devices, Sept. 1991, Electronics Manufacturing Technology Symposium, 1991., Eleventh IEEE/CHMT International, pp. 320-324.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.